

Docket No. : SHIGA7.045APC
Application No. : 10/568,126
Filing Date : February 14, 2006

Customer No.: 20,995

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

REPLY BRIEF

Applicant : Masuda et al.
App. No : 10/568,126
Filed : February 14, 2006
For : POSITIVE PHOTORESIST
COMPOSITION AND RESIST
PATTERN FORMATION
Examiner : Chu, John S Y
Art Unit : 1795

OK TO ENTER: /JSC/
01/23/2009

Mail Stop Reply Brief - Patents
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Examiner's Answer mailed **September 10, 2008**, Applicant submits this Reply Brief.

Status of the Claims begins on page 2 of this paper.

Grounds for Rejection to be Reviewed on Appeal begin on page 3 of this paper.

Appellants' Arguments begin on page 4 of this paper.

Appendix A begins on page 10 of this paper.